Pinch in the vicinity of a meniscus in a thin liquid film

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In a thin liquid film connected to a meniscus, Aradian et al. [1] predict a zone of small thickness, called the pinch, between the meniscus and the film. This pinch is the origin of the marginal regeneration phenomenon observed in the 60s by Mysels in soap films [2] and which is of major importance in describing thin film drainage [3] and therefore their stability.

Thanks to a model experiment, we measure thickness profiles in the pinch zone and highlight the pinch.

Pinch and marginal regeneration



- The pinch (at the bottom of the bubble) destabilizes into thin patches
- The thin patches go up and replace thicker film portions that go down (= drainage): the thick film regenerates in the meniscus as thin film



[3]

Experiment

We deposit a thin film of silicone oil on a silicon wafer by spin-coating. The pinch destabilizing should be prevented by the solid surface. We deposit a glass capillary tube on the film to create a meniscus. We observe the reflection of a white light on the film thanks to a hyperspectral camera.

<u>Creation of thin liquid films</u> Spin-coating



<u>Creation of a meniscus</u> Depositing a capillary horizontally <u>Measurement of the film thickness</u> Interferometric method using a hyperspectral camera (= a line of spectrometers)

The camera is looking at a line that is perpendicular to the capillary













The pinch dynamics are not yet reproducible, and we believe this is partly due to the films getting less and less homogeneous with time, away from the pinch.



Discussion and outlooks

<u>Results:</u>

- We observe the pinch predicted by Aradian et al. [1] in a thin film of silicone oil,
- But its dynamics are not reproducible partly because when the pinch appears, the film has become inhomogeneous.

Ways to improve:

New geometries:

Ring deposited on a wafer to get rid of the edge effects causing inhomogeneities
Vertical rod deposited on a wafer to make the pinch appear faster and to be less subject to the inhomogeneities [4]